

ABSTRACT

According to the present disclosure, an electroconductive resin composition that achieves both storage stability and a low connection resistance value of the cured product is provided. The

5 present disclosure relates to an electroconductive resin composition containing the following components (A) to (E), wherein an organic solvent content is 1% by mass or less with respect to the entire electroconductive resin composition,

10 component (A): an epoxy resin having two or more epoxy groups in one molecule,

component (B): a reactive diluting agent having one epoxy group in one molecule,

component (C): rubber particles,

15 component (D): electroconductive particles containing the following (d-1) and (d-2),

(d-1): plate-shaped silver particles,

(d-2): electroconductive particles other than plate-shaped silver particles, and

component (E): an epoxy curing agent.

20

No Figure